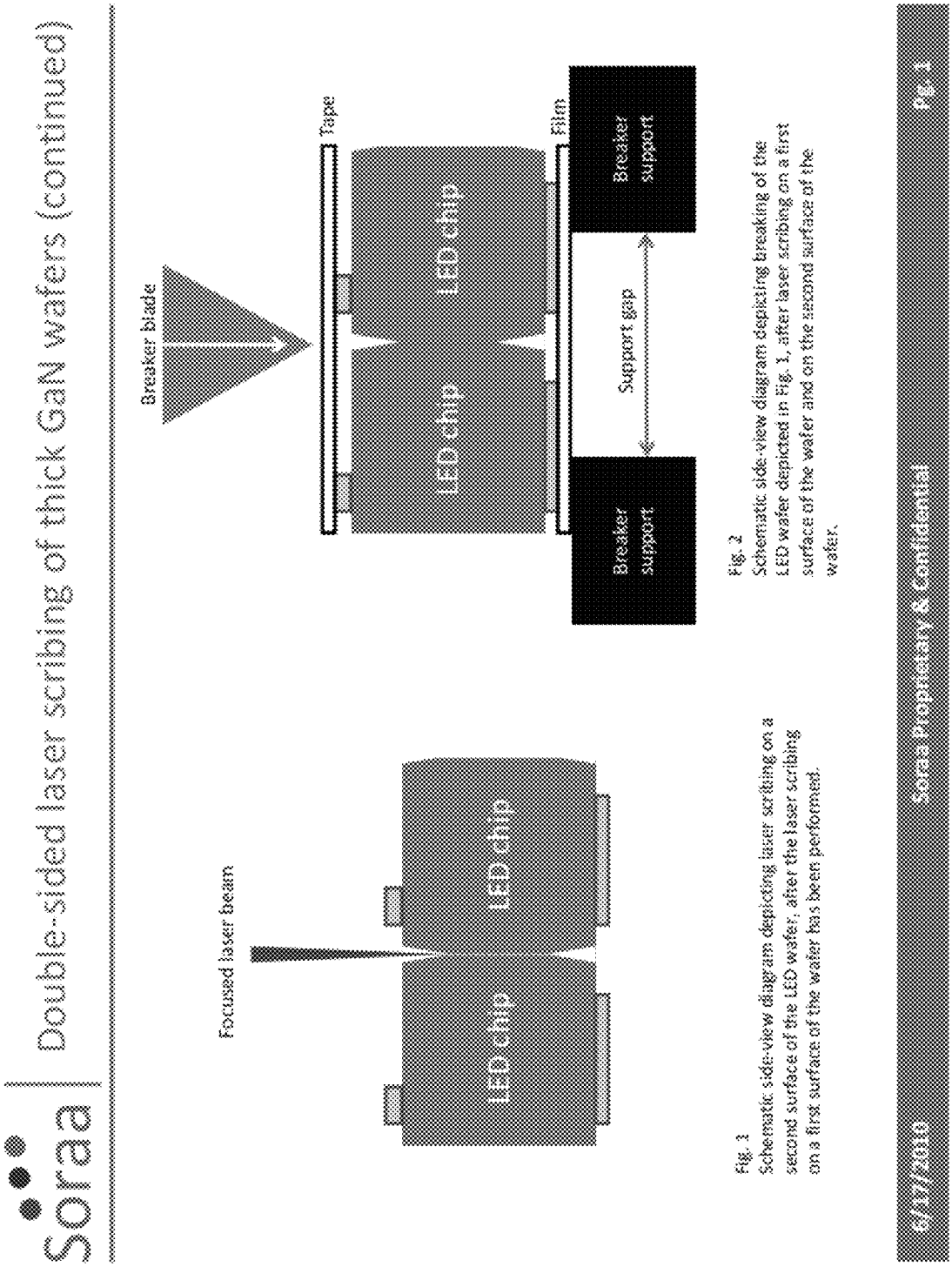
Soraa
Double-sided laser scribing of thick GaN wafers (continued)
Breaker blade
Tape
LED chip
LED chip
Film
Breaker support
Support gap
Breaker support
Focused laser beam
LED chip
LED chip
Fig. 2
Schematic side-view diagram depicting breaking of the LED wafer depicted in Fig. 1, after laser scribing on a first surface of the wafer and on the second surface of the wafer.
Fig. 3
Schematic side-view diagram depicting laser scribing on a second surface of the LED wafer, after the laser scribing on a first surface of the wafer has been performed.
6/17/2010
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Fig. 1